

# FOD2712 Optically Isolated Error Amplifier



#### **Features**

- Optocoupler, precision reference and error amplifier in single package
- 1.240V ± 1% reference
- CTR 100% to 200%
- 2,500V RMS isolation
- VDE approval 136616
- BSI approval 8661 and 8662
- UL approval E90700
- CSA approval 1113643

## **Applications**

- Power system for workstations
- Telecom central office supply
- Telecom bricks

#### Description

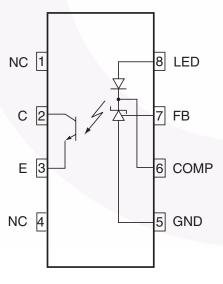
The FOD2712 Optically Isolated Amplifier consists of the popular RC431A precision programmable shunt reference and an optocoupler. The optocoupler is a gallium arsenide (GaAs) light emitting diode optically coupled to a silicon phototransistor. The reference voltage tolerance is 1%. The current transfer ratio (CTR) ranges from 100% to 200%.

It is primarily intended for use as the error amplifier/ reference voltage/optocoupler function in isolated AC to DC power supplies and dc/dc converters.

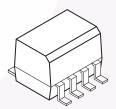
When using the FOD2712, power supply designers can reduce the component count and save space in tightly packaged designs. The tight tolerance reference eliminates the need for adjustments in many applications.

The device comes in a compact 8-pin small outline package.

#### **Schematic**



## **Package Outline**

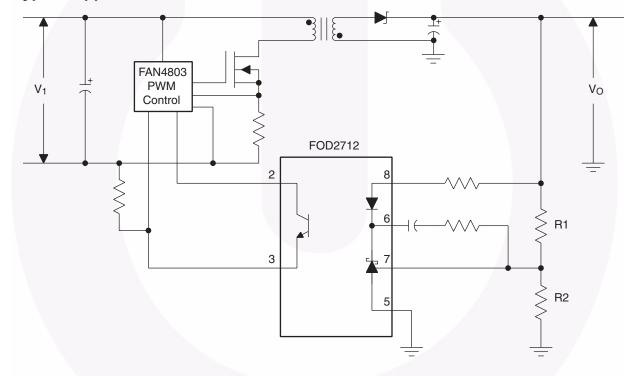


## **Pin Definitions**

Pin Number	Pin Name	Functional Description
1	NC	Not connected
2	С	Phototransistor Collector
3	E	Phototransistor Emitter
4	NC	Not connected
5	GND	Ground
6	COMP	Error Amplifier Compensation. This pin is the output of the error amplifier.*
7	FB	Voltage Feedback. This pin is the inverting input to the error amplifier
8	LED	Anode LED. This pin is the input to the light emitting diode.

<sup>\*</sup>The compensation network must be attached between pins 6 and 7.

## **Typical Application**



## **Absolute Maximum Ratings** (T<sub>A</sub> = 25°C unless otherwise specified)

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

Symbol	Parameter	Value	Units
T <sub>STG</sub>	Storage Temperature	-55 to +125	°C
T <sub>OPR</sub>	Operating Temperature	-40 to +85	°C
	Reflow Temperature Profile (refer to page 14)		
V <sub>LED</sub>	Input Voltage	13.2	V
I <sub>LED</sub>	Input DC Current	20	mA
V <sub>CEO</sub>	Collector-Emitter Voltage	30	V
V <sub>ECO</sub>	Emitter-Collector Voltage	7	V
I <sub>C</sub>	Collector Current	50	mA
PD1	Input Power Dissipation <sup>(1)</sup>	145	mW
PD2	Transistor Power Dissipation <sup>(2)</sup>	85	mW
PD3	Total Power Dissipation <sup>(3)</sup>	145	mW

#### Notes:

- 1. Derate linearly from 25°C at a rate of 2.42mW/°C
- 2. Derate linearly from 25°C at a rate of 1.42mW/°C.
- 3. Derate linearly from 25°C at a rate of 2.42mW/°C.

## **Electrical Characteristics** ( $V_{CC} = 12V$ , $T_A = 25^{\circ}C$ unless otherwise specified)

#### **Input Characteristics**

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
V <sub>F</sub>	LED Forward Voltage	$I_{LED}$ = 10mA, $V_{COMP}$ = $V_{FB}$ (Fig.1)			1.5	V
V <sub>REF</sub>	Reference Voltage	$V_{COMP} = V_{FB}$ , $I_{LED} = 10mA$				
	-40°C to +85°C	(Fig.1)	1.221		1.259	V
	25°C		1.228	1.240	1.252	
V <sub>REF (DEV)</sub>	Deviation of V <sub>REF</sub> over temperature See Note 1	$T_A = -40 \text{ to } +85^{\circ}\text{C}$		4	12	mV
$\frac{\Delta V_{REF}}{\Delta V_{COMP}}$	Ratio of Vref Variation to the Output of the Error Amplifier	$I_{LED}$ = 10 mA, $V_{COMP}$ = $V_{REF}$ to 12V (Fig. 2)		-1.5	-2.7	mV/V
I <sub>REF</sub>	Feedback Input Current	$I_{LED}$ = 10mA, R1 = 10kΩ (Fig. 3)		0.15	0.5	μΑ
I <sub>REF (DEV)</sub>	Deviation of I <sub>REF</sub> Over Temperature See Note 1	T <sub>A</sub> = -40 to +85°C		0.15	0.3	μΑ
I <sub>LED (MIN)</sub>	Minimum Drive Current	V <sub>COMP</sub> = V <sub>FB</sub> (Fig.1)		55	80	μΑ
I <sub>(OFF)</sub>	Off-state Error Amplifier Current	$V_{LED} = 6V, V_{FB} = 0 \text{ (Fig.4)}$		0.001	0.1	μA
IZ <sub>OUT</sub> I	Error Amplifier Output Impedance See Note 2	$V_{COMP} = V_{FB}$ , $I_{LED} = 0.1$ mA to 15mA, f < 1kHZ		0.25		Ω

#### Notes:

1. The deviation parameters V<sub>REF(DEV)</sub> and I<sub>REF(DEV)</sub> are defined as the differences between the maximum and minimum values obtained over the rated temperature range. The average full-range temperature coefficient of the reference input voltage, ΔV<sub>REF</sub>, is defined as:

$$\left|\Delta V_{REF}\right|(ppm/^{\circ}C) \; = \; \frac{\left\{V_{REF(DEV)}/V_{REF}(T_{A} = 25^{\circ}C)\right\} \times 10^{6}}{\Delta T_{A}}$$

where  $\Delta T_A$  is the rated operating free-air temperature range of the device.

2. The dynamic impedance is defined as  $|Z_{OUT}| = \Delta V_{COMP}/\Delta I_{LED}$ . When the device is operating with two external resistors (see Figure 2), the total dynamic impedance of the circuit is given by:

$$\left|Z_{OUT, TOT}\right| = \frac{\Delta V}{\Delta I} \approx \left|Z_{OUT}\right| \times \left[1 + \frac{R1}{R2}\right]$$

## $\textbf{Electrical Characteristics} \ (V_{CC} = 12V, T_A = 25^{\circ}C \ unless \ otherwise \ specified) \ (Continued)$

#### **Output Characteristics**

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
I <sub>CEO</sub>	Collector Dark Current	V <sub>CE</sub> = 10V (Fig. 5)			50	nA
BV <sub>CEO</sub>	Collector-Emitter Voltage Breakdown	I <sub>C</sub> = 1.0mA	70			V
BV <sub>ECO</sub>	Emitter-Collector Voltage Breakdown	I <sub>E</sub> = 100μA	7			V

#### **Transfer Characteristics**

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
CTR	Current Transfer Ratio	$I_{LED} = 10\text{mA}, V_{COMP} = V_{FB},$ $V_{CE} = 5V \text{ (Fig. 6)}$	100		200	%
V <sub>CE (SAT)</sub>	Collector-Emitter Saturation Voltage	$I_{LED}$ = 10mA, $V_{COMP}$ = $V_{FB}$ , $I_{C}$ = 2.5mA (Fig. 6)			0.4	V

#### **Isolation Characteristics**

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
I <sub>I-O</sub>	Input-Output Insulation Leakage Current	RH = 45%, T <sub>A</sub> = 25°C, t = 5s, V <sub>I-O</sub> = 3000 VDC (Note 1)			1.0	μА
V <sub>ISO</sub>	Withstand Insulation Voltage	$RH \le 50\%$ , $T_A = 25$ °C, $t = 1$ min. (Note 1)	2500			Vrms
R <sub>I-O</sub>	Resistance (Input to Output)	V <sub>I-O</sub> = 500 VDC (Note 1)		10 <sup>12</sup>		Ω

#### **Switching Characteristics**

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
B <sub>W</sub>	Bandwidth	Fig. 7		10		kHz
CMH	Common Mode Transient Immunity at Output HIGH	$I_{LED} = 0mA,  V_{cm}  = 10 V_{PP}$ RL = 2.2k $\Omega$ (Fig. 8) (Note 2)		1.0		kV/µs
CML	Common Mode Transient Immunity at Output LOW	$I_{LED} = 10 \text{mA},  V_{cm}  = 10 V_{PP}$ RL = 2.2k $\Omega$ (Fig. 8) (Note 2)		1.0		kV/µs

#### Notes:

- 1. Device is considered as a two terminal device: Pins 1, 2, 3 and 4 are shorted together and Pins 5, 6, 7 and 8 are shorted together.
- 2. Common mode transient immunity at output high is the maximum tolerable (positive) dVcm/dt on the leading edge of the common mode impulse signal, Vcm, to assure that the output will remain high. Common mode transient immunity at output low is the maximum tolerable (negative) dVcm/dt on the trailing edge of the common pulse signal, Vcm, to assure that the output will remain low.

### **Test Circuits**

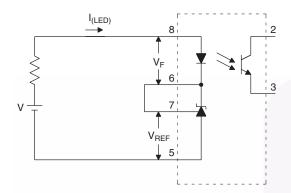


Figure 1.  $V_{REF}$ ,  $V_{F}$ ,  $I_{LED}$  (min) Test Circuit

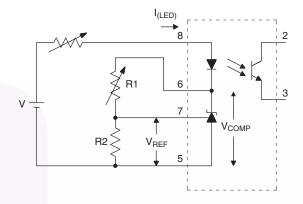


Figure 2.  $\Delta V_{REF}/\Delta V_{COMP}$  Test Circuit

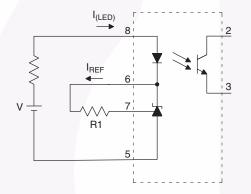


Figure 3. I<sub>REF</sub> Test Circuit

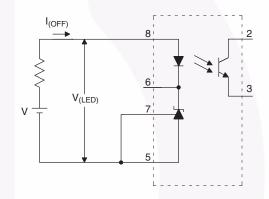


Figure 4. I<sub>(OFF)</sub> Test Circuit

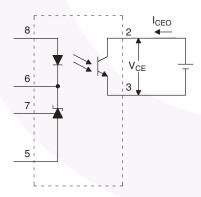


Figure 5. I<sub>CEO</sub> Test Circuit

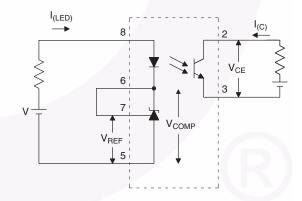


Figure 6. CTR, V<sub>CE(sat)</sub> Test Circuit

## Test Circuits (Continued)

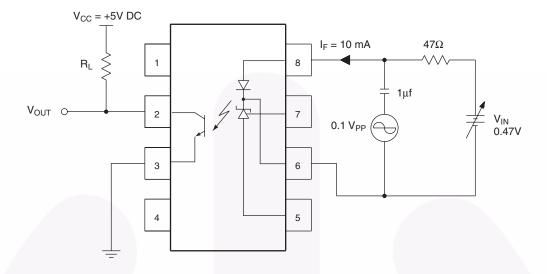


Figure 7. Frequency Response Test Circuit

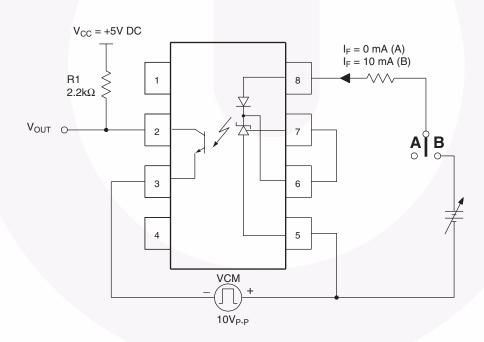
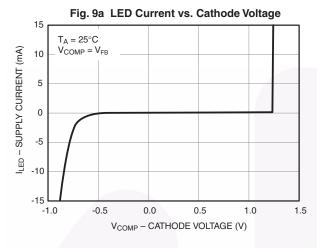


Figure 8. CMH and CML Test Circuit

## **Typical Performance Curves**



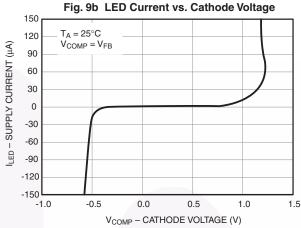


Fig. 10 Reference Voltage vs. Ambient Temperature

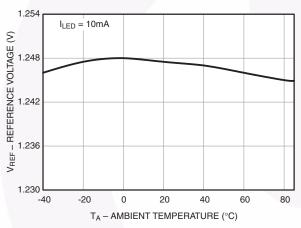


Fig. 11 Reference Current vs. Ambient Temperature

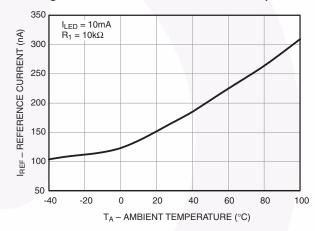
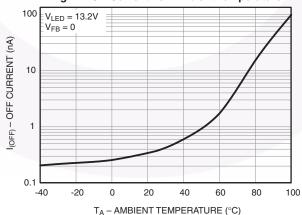


Fig. 12 Off Current vs. Ambient Temperature



## **Typical Performance Curves** (Continued)

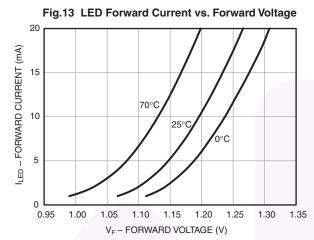


Fig.14 Dark Current vs. Temperature

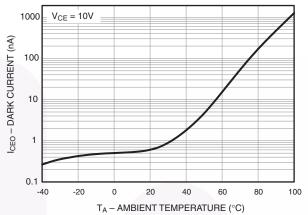


Fig. 15 Collector Current vs. Ambient Temperature

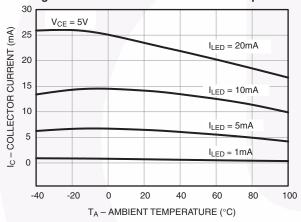


Fig. 16 Current Transfer Ratio vs. LED Current

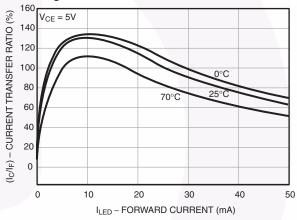
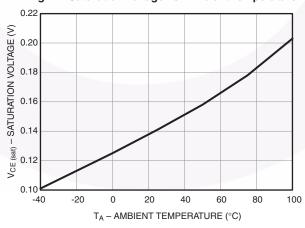
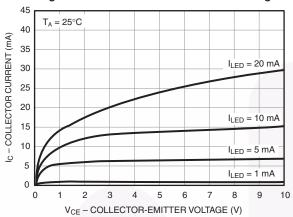


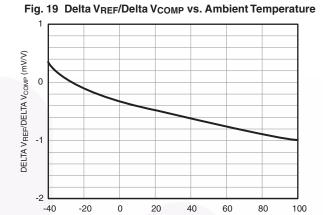
Fig. 17 Saturation Voltage vs. Ambient Temperature



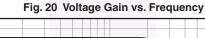
## **Typical Performance Curves** (Continued)

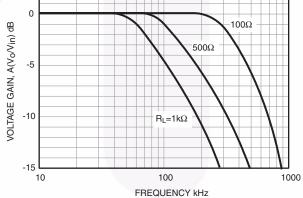
Fig. 18 Collector Current vs. Collector Voltage  $T_A = 25^{\circ}C$ 





T<sub>A</sub> – AMBIENT TEMPERATURE (°C)





#### The FOD2712

The FOD2712 is an optically isolated error amplifier. It incorporates three of the most common elements necessary to make an isolated power supply, a reference voltage, an error amplifier, and an optocoupler. It is functionally equivalent to the popular RC431A shunt voltage regulator plus the CNY17F-3 optocoupler.

### **Powering the Secondary Side**

The LED pin in the FOD2712 powers the secondary side, and in particular provides the current to run the LED. The actual structure of the FOD2712 dictates the minimum voltage that can be applied to the LED pin: The error amplifier output has a minimum of the reference voltage, and the LED is in series with that. Minimum voltage applied to the LED pin is thus 1.24V + 1.5V = 2.74V. This voltage can be generated either directly from the output of the converter, or else from a slaved secondary winding. The secondary winding will not affect regulation, as the input to the FB pin may still be taken from the output winding.

The LED pin needs to be fed through a current limiting resistor. The value of the resistor sets the amount of current through the LED, and thus must be carefully selected in conjunction with the selection of the primary side resistor.

#### **Feedback**

Output voltage of a converter is determined by selecting a resistor divider from the regulated output to the FB pin. The FOD2712 attempts to regulate its FB pin to the reference voltage, 1.24V. The ratio of the two resistors should thus be:

$$\frac{R_{TOP}}{R_{BOTTOM}} = \frac{V_{OUT}}{V_{REF}} - 1$$

The absolute value of the top resistor is set by the input offset current of  $0.8\mu A$ . To achieve 1% accuracy, the resistance of  $R_{TOP}$  should be:

$$\frac{V_{OUT} - 1.24}{R_{TOP}} > 80 \mu A$$

## Compensation

The compensation pin of the FOD2712 provides the opportunity for the designer to design the frequency response of the converter. A compensation network may be placed between the COMP pin and the FB pin. In typical low-bandwidth systems, a 0.1µF capacitor may be used. For converters with more stringent requirements, a network should be designed based on measurements of the system's loop. An excellent reference for this process may be found in "Practical Design of Power Supplies" by Ron Lenk, IEEE Press, 1998.

#### **Secondary Ground**

The GND pin should be connected to the secondary ground of the converter.

#### **No Connect Pins**

The NC pins have no internal connection. They should not have any connection to the secondary side, as this may compromise the isolation structure.

#### **Photo-Transistor**

The Photo-transistor is the output of the FOD2712. In a normal configuration the collector will be attached to a pull-up resistor and the emitter grounded. There is no base connection necessary.

The value of the pull-up resistor, and the current limiting resistor feeding the LED, must be carefully selected to account for voltage range accepted by the PWM IC, and for the variation in current transfer ratio (CTR) of the opto-isolator itself.

**Example:** The voltage feeding the LED pins is +12V, the voltage feeding the collector pull-up is +10V, and the PWM IC is the Fairchild KA1H0680, which has a 5V reference. If we select a  $10K\Omega$  resistor for the LED, the maximum current the LED can see is:

$$(12V-2.74V)/10K\Omega = 926\mu A.$$

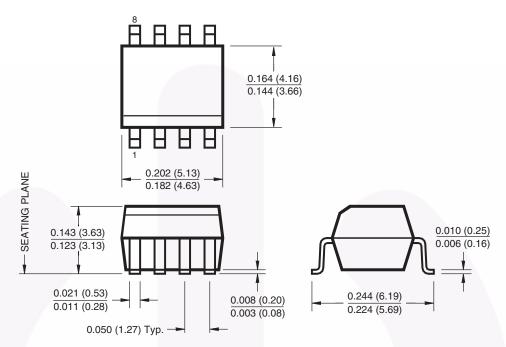
The CTR of the opto-isolator is a minimum of 100%, and so the minimum collector current of the photo-transistor when the diode is full on is also 926 $\mu$ A. The collector resistor must thus be such that:

$$\frac{10V-5V}{R_{COLLECTOR}} < 926 \mu A \text{ or } R_{COLLECTOR} > 5.4 K\Omega;$$

select  $10K\Omega$  to allow some margin.

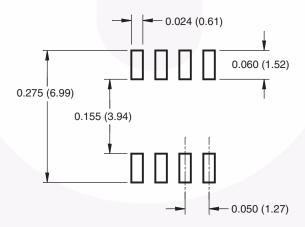
## **Package Dimensions**

#### 8-pin SOIC Surface Mount



Lead Coplanarity: 0.004 (0.10) MAX

#### **Recommended Pad Layout**



Dimensions in inches (mm).

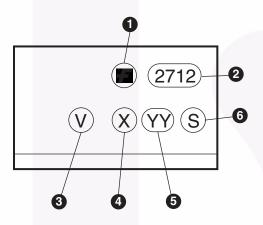
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## **Ordering Information**

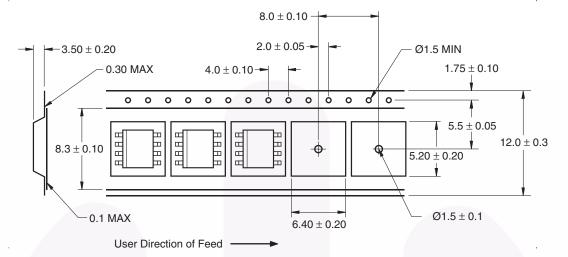
Option	Order Entry Identifier	Description
V	V	VDE 0884
R1	R1	Tape and reel (500 units per reel)
R1V	R1V	VDE 0884, Tape and reel (500 units per reel)
R2	R2	Tape and reel (2500 units per reel)
R2V	R2V	VDE 0884, Tape and reel (2500 units per reel)

# **Marking Information**



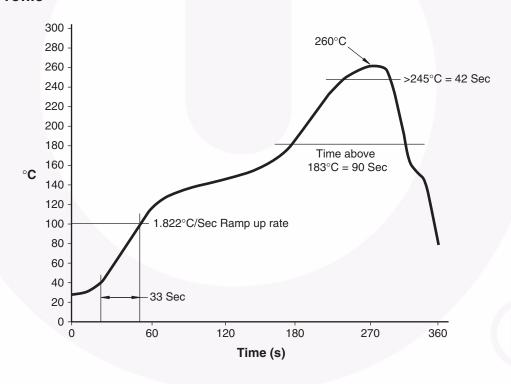
Defini	tions
1	Fairchild logo
2	Device number
3	VDE mark (Note: Only appears on parts ordered with VDE option – See order entry table)
4	One digit year code, e.g., '3'
5	Two digit work week ranging from '01' to '53'
6	Assembly package code

## **Carrier Tape Specifications**



Dimensions in mm

### **Reflow Profile**







CorePLUS™ CorePOWER™ CROSSVOLT™

EZSWITCH™ \*

Current Transfer Logic™ EcoSPARK<sup>®</sup> EfficentMax™

airchild<sup>®</sup>

airchild Semiconductor® FACT Quiet Series™

FACT<sup>'</sup> FAST<sup>®</sup> astvCore™ FlashWriter<sup>®</sup> FPS™ F-PFS™

Global Power Resource SM

Green FPS™ Green FPS™e-Series™

GTO™

IntelliMAX™ ISOPI ANAR™ MegaBuck™

MICROCOUPLER™ MicroFET™

MicroPak™ MillerDrive™ MotionMax™ Motion-SPM™ OPTOLOGIC® OPTOPLANAR®

PDP SPM™ Power-SPM™ PowerTrench® PowerXS™

OFET<sup>6</sup> QS™ Quiet Series™ RapidConfigure™

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STEALTH™ SuperFET™ SuperSOT™3 SuperSOT™6 SuperSOT™-8 . SupreMOS™ SyncFET™

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- A critical component in any component of a life support, device, or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

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